

# MATERIAL DECLARATION SHEET



Material	MF-FSMF010X
Product Line	Multifuse
Revision Date	26-Nov-10
Revision	A
RoHS Compliant	Yes
Halogen free compliant	Yes

No.	Breakdown of part (eg Lead, Ceramic body, coating, plating, additive)	Material/substance name (eg.Sn alloy, Cu Copper)	Material/ substance weight in grams (±0.1%)	CAS No. / Int. Identifier	Material /substance weight %	Sum(%)
1	Carbon Black	Carbon	0.0001029	1333-86-4	6.30%	6.30%
2	Copper plating	Copper	0.0002214	7440-50-8	13.56%	13.56%
3	Foil	Copper	0.0009424	7440-50-8	57.72%	60.76%
		Nickel	0.0000496	7440-02-0	3.04%	
4	PCB Foil	Copper	0.0001861	7440-50-8	11.40%	11.40%
5	Polymer	Fluorine Type Homopolymer	0.0000912	9002-88-4	5.58%	5.59%
		Proprietary Additives	0.0000001	-	0.01%	
6	Prepreg	Epoxy	0.0000027	35948-25-5	0.16%	0.27%
		Glass Fiber	0.0000018	65997-17-3	0.11%	
7	Soldering plating	Nickel	0.0000334	7440-02-0	2.05%	2.06%
		Gold	0.0000001	7440-57-5	0.01%	
8	Protection layer	Epoxy	0.0000009	-	0.05%	0.05%

Total weight (grams)	0.0016325	Total	100%	100%
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# MATERIAL DECLARATION SHEET



Material	MF-FSMF020X
Product Line	Multifuse
Revision Date	March.06, 2009
Revision	A
RoHS Compliant	Yes
Halogen free compliant	Yes

No.	Breakdown of part (eg Lead, Ceramic body, coating, plating, additive)	Material/substance name (eg.Sn alloy, Cu Copper)	Material/ substance weight in grams (±0.1%)	CAS No. / Int. Identifier	Material /substance weight %	Sum(%)
1	Carbon Black	Carbon	0.0000741	1333-86-4	4.69%	4.69%
2	Copper plating	Copper	0.0002214	7440-50-8	14.03%	14.03%
3	Foil	Copper	0.0009424	7440-50-8	59.71%	62.86%
		Nickel	0.0000496	7440-02-0	3.14%	
4	PCB Foil	Copper	0.0001861	7440-50-8	11.79%	11.79%
5	Polymer	Polyethylene Homopolymer	0.0000656	9002-88-4	4.16%	4.16%
		Proprietary Additives	0.0000001	-	0.01%	
6	Prepreg	Epoxy	0.0000027	35948-25-5	0.17%	0.28%
		Glass fiber	0.0000018	65997-17-3	0.11%	
7	Packing-Carrier Tape	Polystyrene	N/A	9003-53-6	-	-
		Polyethylene Homopolymer	N/A	9002-88-4	-	-
8	Packing-Cover Tape	Polyethylene terephthalate	N/A	25038-59-9	-	-
		Polyethylene Homopolymer	N/A	9002-88-4	-	-
9	Soldering plating	Nickel	0.0000334	7440-02-0	2.12%	2.13%
		Gold	0.0000001	7440-57-5	0.01%	
10	Protection layer	Epoxy	0.0000009	-	0.06%	0.06%

Total weight (grams)	0.0015781	Total	100%	100%
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# MATERIAL DECLARATION SHEET



Material	MF-FSMF035X
Product Line	Multifuse
Revision Date	March.06, 2009
Revision	A
RoHS Compliant	Yes
Halogen free compliant	Yes

No.	Breakdown of part (eg Lead, Ceramic body, coating, plating, additive)	Material/substance name (eg.Sn alloy, Cu Copper)	Material/ substance weight in grams (±0.1%)	CAS No. / Int. Identifier	Material /substance weight %	Sum(%)
1	Carbon Black	Carbon	0.0000741	1333-86-4	4.69%	4.69%
2	Copper plating	Copper	0.0002214	7440-50-8	14.03%	14.03%
3	Foil	Copper	0.0009424	7440-50-8	59.71%	62.86%
		Nickel	0.0000496	7440-02-0	3.14%	
4	PCB Foil	Copper	0.0001861	7440-50-8	11.79%	11.79%
5	Polymer	Polyethylene Homopolymer	0.0000656	9002-88-4	4.16%	4.16%
		Proprietary Additives	0.0000001	-	0.01%	
6	Prepreg	Epoxy	0.0000027	35948-25-5	0.17%	0.28%
		Glass fiber	0.0000018	65997-17-3	0.11%	
7	Packing-Carrier Tape	Polystyrene	N/A	9003-53-6	N/A	N/A
		Polyethylene Homopolymer	N/A	9002-88-4	N/A	N/A
8	Packing-Cover Tape	Polyethylene terephthalate	N/A	25038-59-9	N/A	N/A
		Polyethylene Homopolymer	N/A	9002-88-4	N/A	N/A
9	Soldering plating	Nickel	0.0000334	7440-02-0	2.12%	2.13%
		Gold	0.0000001	7440-57-5	0.01%	
10	Protection layer	Epoxy	0.0000009	-	0.06%	0.06%

Total weight (grams)	0.0015781	Total	100%	100%
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# MATERIAL DECLARATION SHEET



Material	MF-FSMF050X
Product Line	Multifuse
Revision Date	March.06, 2009
Revision	A
RoHS Compliant	Yes
Halogen free compliant	Yes

No.	Breakdown of part (eg Lead, Ceramic body, coating, plating, additive)	Material/substance name (eg.Sn alloy, Cu Copper)	Material/ substance weight in grams (±0.1%)	CAS No. / Int. Identifier	Material /substance weight %	Sum(%)
1	Carbon Black	Carbon	0.0001482	1333-86-4	5.46%	5.46%
2	Copper plating	Copper	0.0002214	7440-50-8	8.16%	8.16%
3	Foil	Copper	0.0018847	7440-50-8	69.49%	73.15%
		Nickel	0.0000992	7440-02-0	3.66%	
4	PCB Foil	Copper	0.0001861	7440-50-8	6.86%	6.86%
5	Polymer	Polyethylene Homopolymer	0.0001313	9002-88-4	4.84%	4.85%
		Proprietary Additives	0.0000002	-	0.01%	
6	Prepreg	Epoxy	0.0000040	35948-25-5	0.15%	0.25%
		Glass fiber	0.0000027	65997-17-3	0.10%	
7	Packing-Carrier Tape	Polystyrene	N/A	9003-53-6	N/A	N/A
		Polyethylene Homopolymer	N/A	9002-88-4	N/A	N/A
8	Packing-Cover Tape	Polyethylene terephthalate	N/A	25038-59-9	N/A	N/A
		Polyethylene Homopolymer	N/A	9002-88-4	N/A	N/A
9	Soldering plating	Nickel	0.0000334	7440-02-0	1.23%	1.24%
		Gold	0.0000001	7440-57-5	0.01%	
10	Protection layer	Epoxy	0.0000009	-	0.03%	0.03%

Total weight (grams)	0.0027121	Total	100%	100%
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